

Title (en)

METHOD FOR CONDUCTIVELY CONNECTING A COMPONENT ON A TRANSPARENT SUBSTRATE

Title (de)

VERFAHREN ZUR LEITENDEN VERBINDUNG EINES BAUELEMENTES AUF EINEM TRANSPARENTEN SUBSTRAT

Title (fr)

PROCÉDÉ DESTINÉ À RELIER DE MANIÈRE CONDUCTRICE UN COMPOSANT SUR UN SUBSTRAT TRANSPARENT

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2010118821A1] The invention relates to a method for conductively connecting an electrical component having at least one conductive layer. The conductive layer is applied to a substrate which is essentially transparent in the visible wavelength zone of light, comprising the following steps: the electrical component or the conductive layer is provided with a lead material in the area where the component is to be connected to the conductive layer; the lead material is provided with energy supplied by an energy source such that the lead material melts, and a non-detachable, material-bonded, conductive connection between the electrical component and the conductive layer is formed.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

See references of WO 2010118821A1

Citation (examination)

ATHWAL I S ET AL: "Optical transmission of fluorine-doped tin oxide films", SOLID STATE ELECTRONICS, ELSEVIER SCIENCE PUBLISHERS, BARKING, GB, vol. 28, no. 11, 1 November 1985 (1985-11-01), pages 1165, XP025754850, ISSN: 0038-1101, [retrieved on 19851101], DOI: 10.1016/0038-1101(85)90197-2

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